## FEATURES

- 12-bit resolution
- 1.0 and 1.5 MHz throughput rates
- Small 44-pin Leaded Chip Carrier
- Single +5V supply
- Low power, 75 and 200 mW maximum
- Low power "standby" mode
- Outstanding dynamic performance
- No missing codes over temperature
- Built-in sample-and-hold
- Optional two-channel input multiplexer
- Ideal for both time and frequency-domain applications


## GENERAL DESCRIPTION

The ADS-230 and ADS-231 are 12-bit, high speed CMOS sampling analog-to-digital converters capable of minimum sampling rates of 1.0 and 1.5 MHz , respectively. Both models feature excellent dynamic performance including a typical SNR of 72dB for the ADS-230 and 70dB for the ADS-231.

The ADS-230 and ADS-231 are packaged in a small 44-pin plastic Leaded Chip Carrier (LCC). Each model contains a fast-settling sample/hold amplifier, a multipass (three-step flash) A/D converter, timing and control logic, three-state outputs, a two-channel multiplexer, and digital error correction circuitry. Digital input and output levels are TTL.
Requiring only a single +5 V supply, the ADS-230 typically dissipates only 60 mW and the ADS-231 only 170 mW . Both models offer a low-power "standby" mode resulting in typical power dissipations of $100 \mu \mathrm{~W}$ and $250 \mu \mathrm{~W}$, respectively. The units offer a maximum unipolar input range of 0 to +5 V . The exact value of the input range is determined by an externally applied reference voltage. Both models operate over the extended -40 to $+85^{\circ} \mathrm{C}$ temperature range.


INPUT/OUTPUT CONNECTIONS

| PIN | FUNCTION | PIN | FUNCTION |
| :---: | :--- | :--- | :--- |
| 1 | AGND | 44 | AVs |
| 2 | VBS | 43 | BIT 1 (MSB) |
| 3 | VB | 42 | BIT 2 |
| 4 | VR/16 | 41 | BIT 3 |
| 5 | VT | 40 | BIT 4 |
| 6 | VTS | 39 | BIT 5 |
| 7 | CH1IN | 38 | BIT 6 |
| 8 | NC | 37 | BIT 7 |
| 9 | CH2IN | 36 | BIT 8 |
| 10 | NC | 35 | BIT 9 |
| 11 | MUX OUT | 34 | NC |
| 12 | ANALOG INPUT | 33 | BIT 10 |
| 13 | AGND | 32 | BIT 11 |
| 14 | AVs | 31 | BIT 12 (LSB) |
| 15 | DGND C | 30 | EOC |
| 16 | SEL | 29 | NT |
| 17 | PD | 28 | NC |
| 18 | DGND C | 27 | DGND D |
| 19 | MD | 26 | DGND C |
| 20 | OE | 25 | DVs |
| 21 | RD | 24 | TEST |
| 22 | S/H | 23 | CS |



Figure 1. ADS-220/-231 Simplified Block Diagram

## ABSOLUTE MAXIMUM RATINGS

| PARAMETERS | LIMITS | UNITS |
| :--- | :---: | :---: |
| Supply Voltages |  |  |
| $\quad$ (Vs = AVs = DVs) | -0.3 to +6 | V |
| Input or Output Voltage, any pin | -0.3 to Vs +0.3 | V |
| Input Current, any pin © | 25 | mA |
| Total Package Input Current, (1) | 50 | mA |
| Power Dissipation, (2) | 875 | mW |
| ESD Susceptibilty, (3) | 2000 | V |
| Soldering, Infrared, 15 seconds | +300 | ${ }^{\circ} \mathrm{C}$ |

## PHYSICAL/ENVIRONMENTAL

| PARAMETERS | MIN. | TYP. | MAX. | UNITS |
| :--- | :---: | :---: | :---: | :---: |
| Operating Temp. Range TA $=\mathrm{TJ}$ | -40 | - | +85 | ${ }^{\circ} \mathrm{C}$ |
| Thermal Impedance, $\theta \mathrm{Ja}$ | - | 55 | - | ${ }^{\circ} \mathrm{C} /$ Watt |
| Maximum Junction Temp. TJMAX | - | - | +150 | ${ }^{\circ} \mathrm{C}$ |
| Storage Temperature Range | -65 | - | +150 | ${ }^{\circ} \mathrm{C}$ |
| Package Type | 44 -pin Plastic Leaded Chip Carrier |  |  |  |

## FUNCTIONAL SPECIFICATIONS

(The following specifications apply for $\mathrm{T}_{\mathrm{A}}=\mathrm{T} J=25^{\circ} \mathrm{C}, \mathrm{DVS}=\mathrm{AV} s=5.0 \mathrm{~V}, \mathrm{~V} T S=+4.096 \mathrm{~V}, \mathrm{VBS}=\mathrm{AGND}, \mathrm{Rs}=250 \mathrm{hms}$ and $\mathrm{Fs}=1.0 / 1.5 \mathrm{MHz}$ for the ADS -230/231 respectively, unless otherwise specified.)

\begin{tabular}{|c|c|c|c|c|c|c|c|}
\hline \& \multicolumn{3}{|c|}{ADS-230} \& \multicolumn{3}{|c|}{ADS-231} \& \\
\hline \& \(+25^{\circ} \mathrm{C}\) \& \multicolumn{2}{|l|}{-40 to \(+85^{\circ} \mathrm{C}\)} \& \(+25^{\circ} \mathrm{C}\) \& \multicolumn{2}{|r|}{-40 to \(+85^{\circ} \mathrm{C}\)} \& \\
\hline ANALOG INPUT \& TYP. \& MIN. \& MAX. \& TYP. \& MIN. \& MAX. \& UNITS \\
\hline \begin{tabular}{l}
Input Voltage Range (Pins 7, 9, 12) \\
Input Leakage Current \\
Input Capacitance \\
MUX On/Off-Channel Leakage \\
MUX Input Capacitance \\
MUX Off-Channel Isolation \\
\(\mathrm{FIN}=100 \mathrm{kHz},-0 \mathrm{~dB}\)
\end{tabular} \& \[
\begin{gathered}
- \\
0.1 \\
25 \\
0.1 \\
7 \\
\\
92
\end{gathered}
\] \& \[
\begin{gathered}
-0.05 \\
- \\
- \\
- \\
-
\end{gathered}
\] \& \[
\begin{gathered}
\text { AVs+0.05 } \\
3 \\
- \\
3 \\
- \\
-
\end{gathered}
\] \& \[
\begin{gathered}
- \\
0.1 \\
25 \\
0.1 \\
7 \\
\\
\\
92
\end{gathered}
\] \& \begin{tabular}{c}
-0.05 \\
- \\
- \\
- \\
\hline
\end{tabular} \& \[
\begin{gathered}
\mathrm{AVs}+0.05 \\
3 \\
- \\
-
\end{gathered}
\] \& \begin{tabular}{l}
V \\
\(\mu \mathrm{A}\) \\
pF \\
\(\mu \mathrm{A}\) \\
pF \\
dB
\end{tabular} \\
\hline \multicolumn{8}{|l|}{REFERENCE INPUT} \\
\hline Reference Input + (Pin 6), VTS Reference Input - (Pin 2), VBS Reference Resistance \& \[
\frac{-}{750}
\] \& \[
\begin{gathered}
\overline{0} \\
500
\end{gathered}
\] \& \[
\begin{gathered}
\mathrm{AVs} \\
\frac{-}{1000}
\end{gathered}
\] \& \begin{tabular}{c}
\(\square\) \\
\hline 750
\end{tabular} \& \[
\begin{gathered}
\overline{0} \\
500
\end{gathered}
\] \& \[
\begin{gathered}
\text { AVs } \\
\frac{-}{1000}
\end{gathered}
\] \& \[
\begin{gathered}
\text { V } \\
\text { V } \\
\text { Ohms }
\end{gathered}
\] \\
\hline \multicolumn{8}{|l|}{DIGITAL INPUT} \\
\hline \begin{tabular}{l}
Logic Levels \\
Logic "1", Vs \(=5.5 \mathrm{~V}\) \\
Logic " 0 ", Vs \(=4.5 \mathrm{~V}\) \\
Logic Loading "1" \\
Logic Loading "0" \\
Digital Input Capacitance \\
S/A Pulse Width (4), ts/H
\end{tabular} \& \[
\begin{gathered}
- \\
\hline 0.1 \\
0.1 \\
4 \\
-
\end{gathered}
\] \& \begin{tabular}{l}
2 \\
- \\
- \\
- \\
- \\
\hline
\end{tabular} \& \[
\begin{gathered}
- \\
0.8 \\
1 \\
1 \\
- \\
550
\end{gathered}
\] \& \[
\begin{gathered}
- \\
\hline-1 \\
0.1 \\
4
\end{gathered}
\] \& 2
-
-
-
- \& \[
\begin{gathered}
\overline{0.8} \\
1 \\
1 \\
- \\
400
\end{gathered}
\] \& \[
\begin{gathered}
\mathrm{V} \\
\mathrm{~V} \\
\mu \mathrm{~A} \\
\mu \mathrm{~A} \\
\mathrm{pF} \\
\mathrm{~ns}
\end{gathered}
\] \\
\hline \multicolumn{8}{|l|}{STATIC PERFORMANCE} \\
\hline \begin{tabular}{l}
Resolution \\
Integral Nonlinearity \\
Differential Nonlinearity Error \\
No Missing Codes \\
Offset Error \\
Gain Error \\
Power Supply Sensitivity, ( \(\pm 10 \%\) )
\end{tabular} \& \[
\begin{gathered}
\pm 0.4 \\
\pm 0.4 \\
- \\
\pm 0.3 \\
\pm 0.2
\end{gathered}
\] \& 12
-
-
12
-
- \& \[
\begin{gathered}
\pm 1.5 \\
\pm 0.95 \\
\hline- \\
\pm 2.0 \\
\pm 1.5 \\
\pm 1.0
\end{gathered}
\] \& \[
\begin{gathered}
\pm 0.4 \\
\pm 0.4 \\
- \\
\pm 0.3 \\
\pm 0.3
\end{gathered}
\] \& 12
-
-
12
-
- \& \[
\begin{gathered}
\pm 1.5 \\
\pm 0.95 \\
- \\
\pm 2.0 \\
\pm 1.5 \\
\pm 0.75
\end{gathered}
\] \& \begin{tabular}{l}
Bits \\
LSB \\
LSB \\
Bits \\
LSB \\
LSB \\
LSB
\end{tabular} \\
\hline \multicolumn{8}{|l|}{DYNAMIC PERFORMANCE (5)} \\
\hline \begin{tabular}{l}
Total Harmonic Distortion (-0dB)
Fin = 100kHz © \\
Signal-to-Noise Ratio \\
(wo/distortion, -0 dB ) \(\mathrm{Fin}=100 \mathrm{kHz}\) \\
Signal-to-Noise Ratio (7) \\
(\& distortion, -0dB) Fin = 100kHz \\
Two-Tone Intermodulation Distortion
\[
\mathrm{Fin}=102.3,102.7 \mathrm{kHz},(-0 \mathrm{~dB})
\] \\
Aperature Delay Time, (tad) \\
A/D Conversion Rate
\end{tabular} \& \[
\begin{gathered}
-82 \\
72 \\
71 \\
-80 \\
20
\end{gathered}
\] \& \begin{tabular}{c}
- \\
69.5 \\
68 \\
- \\
- \\
\hline 1
\end{tabular} \& -70
-
-
-
- \& -80
70
70
-80
20
- \& \begin{tabular}{c}
- \\
67.5 \\
67 \\
- \\
\hline-
\end{tabular} \& -70
-
-
-
- \& dB
dB
dB

$d B$
$n s$
$M H z$ <br>
\hline
\end{tabular}



## PIN DESCRIPTIONS

AVs, DVs

AGND, DGNDC, DGNDD

BIT 1 - BIT 12
CH1ın, CH2ın
MUX OUT
ANALOG INPUT
SEL

MD
TEST
$\overline{\mathrm{CS}}$
$\overline{\mathrm{INT}}$
$\overline{\mathrm{EOC}}$
$\overline{R D}$

OE
$S / \bar{H}$
$\overline{P D}$
$V_{R / 16}$
VT, VB

VTS, VBS

These are the analog and digital power supply input pins. They should all be connected to the same voltage source. Both AVs pins should be bypassed to AGND and the DVs pin to DGNDD. Bypass using a $0.1 \mu \mathrm{~F}$ ceramic capacitor in parallel with a $10 \mu \mathrm{~F}$ tantalum capacitor.

These are the analog and digital ground pins. All of the ground pins should be returned to the same potential and connected to a stable, noise-free system ground. AGND is the analog ground. DGNDC is the ground for the digital control lines. DGNDD is the digital ground for the output data bus.

These are the three-state data output pins. Output is enabled by $\overline{\mathrm{RD}}, \overline{\mathrm{CS}}$, and OE .
These are the analog input pins to the internal input multiplexer.
This is the output of the internal multiplexer,
This is the direct input to the sampling A to D converter.
This is the multiplexer channel select pin. The input is selected based on the state of SEL when EOC transitions low. A low selects channel one and a high selects channel two. See Table 1.

Connect to DGNDC
Connect to DVs.
This is the Chip Select control input. When low, this pin enables the $\overline{R D}, S / \bar{H}$ and $O E$ inputs. This pin can be tied low.

This is the Interrupt output pin. When using the Interrupt Interface Mode, this output goes low when a conversion is completed and indicates that the data is available in the output latches. This output is always high when $\overline{\mathrm{RD}}$ is held low. Refer to the Timing Diagrams.

This is the End of Conversion output pin. $\overline{\mathrm{EOC}}$ is low during a conversion.
This is the $\overline{R e a d}$ control input pin. When $\overline{\mathrm{RD}}$ and $\overline{\mathrm{CS}}$ are low, the $\overline{\mathrm{INT}}$ output is reset and, if $\overline{\mathrm{EOC}}$ is high, data appears on the data bus. This pin can be tied low.

This is the Output Enable control input pin. The data output pins are in the high impedance state when OE is low. Data appears when OE is high and $\overline{\mathrm{CS}}$ and $\overline{\mathrm{RD}}$ are both low. This pin can be tied high.

This is the Sample and $\overline{\text { Hold }}$ control input pin. When $\overline{\mathrm{CS}}$ is low a new conversion is initiated by the falling edge of this input.

This is the Power Down control input pin. This pin is held high for normal operation. When the input is low, the $A$ to $D$ converter goes into power standby mode.

Bypass this pin to AGND using a $0.1 \mu \mathrm{~F}$ ceramic capacitor.
These are the positive (top) and negative (bottom) voltage reference force input pins, respectively.

These are the positive (top) and negative (bottom) voltage reference sense pins, respectively.

## TECHNICAL NOTES

## The Analog Input

For maximum performance, the source impedance driving the input of the ADS-230/-231 should be as low as possible. A source impedance of less than 100 ohms is recommended. See the Typical Performance Curves.
If the signal source has high output impedance, the output should be buffered with an op-amp capable of driving a switched $25 \mathrm{pF} / 100 \mathrm{ohm}$ load. Any ringing or instability of the op-amp during the sampling period can cause conversion errors.
Using a high-speed buffer also improves the THD performance when using the internal MUX. The MUX onresistance is non-linear over the range of the input voltage; this causes the RC time constant of the equivalent circuit shown in Figure 2 to vary with input voltage. This results in harmonic distortion with increasing frequency. Inserting a buffer between the MUX OUT and ANALOG INPUT terminals will eliminate the loading on Rmux and significantly reduce THD.
The analog input of the ADS-230/-231 can be modeled as shown in Figure 2. The S/H switch is closed during the sample period, and open during hold. The hold capacitor (Сн) has to be charged to the input voltage by the source within the sample period. The source impedance (Rs) will directly effect the charge time. If Rs is too large, the voltage across CH will not settle to within $1 / 2$ LSB's of the source voltage before conversion begins. This will result in conversion errors.
The combination of Rs, Rmux, Rsw and $\mathrm{C}_{\mathrm{h}}$ form a low-pass filter. Therefore, minimizing Rs will increase the frequency response of the converter.

The settling time to $n$ bits is:

$$
\text { tsettle }=(R s+R M u x+R s w) * H^{*} n * \ln (2)
$$

The bandwidth of the input circuit is:

$$
F(-3 \mathrm{~dB})=1 /[2 \text { * } 3.14 \text { * }(\mathrm{Rs}+\mathrm{Rmux}+\mathrm{Rsw}) \text { * } \mathrm{CH}]
$$

## Internal Multiplexer

Both the ADS-230 and ADS-231 have an internal multiplexer that is controlled by the logic level on the SEL pin when EOC goes low. See the timing diagrams. The MUX setup and hold times can be determined from the following:

$$
\begin{aligned}
& \mathrm{tMS}(\mathrm{wrt} \mathrm{~S} / \mathrm{H})=\mathrm{tMS}-\mathrm{tEOC}(\mathrm{~min}) \\
& \text { tMS (wrt S/H) }=50-60 \\
& \mathrm{tMS}(\text { wrt } \mathrm{S} / \mathrm{H})=-10 \mathrm{~ns} \\
& \left.\mathrm{tmH}_{(\text {wrt }} \mathrm{S} / \mathrm{H}\right)=\mathrm{tMH}+\mathrm{tEOC}(\text { max }) \\
& \left.\mathrm{tmH}_{(\text {wrt }} \mathrm{S} / \mathrm{H}\right)=50+125 \\
& \left.\mathrm{tmH}_{\mathrm{Mrt}} \mathrm{~S} / \mathrm{H}\right)=175 \mathrm{~ns}
\end{aligned}
$$

Note that the -10 ns indicates that data on SEL must be valid within 10 ns of the $\mathrm{S} / \overline{\mathrm{H}}$ pulse going low in order to meet the setup time requirements. SEL must be valid for the length of time determined by the following equation:

$$
\left(\text { tms }^{2}+\mathrm{tEOC}(\text { max })\right)-(\mathrm{tms}-\text { tEOC }(\text { min }))=185 \mathrm{~ns}
$$

Table 1 shows the coding for MUX channel selection.
The output of the MUX is available at the MUX OUT pin. This output allows the user to perform additional signal processing, such as buffering, filtering or gain, before the signal is brought to the ANALOG INPUT pin. If signal processing is not required connect the MUX OUT pin directly to the ANALOG INPUT pin.

## Table 1. Internal Multiplexer Programming

| SEL | Channel |
| :---: | :---: |
| 0 | CH 1 IN |
| 1 | CH 2 IN |



Figure 2. ADS-230/-231 Input Stage Model


Figure 3. Reference Force Input Only


Figure 4. Ladder Reference Force and Sense Inputs

## Reference Inputs

Reference voltages are applied to the fully differential $\mathrm{V}_{T}$ and $\mathrm{V}_{\mathrm{B}}$ reference input pins. The resistance of the reference ladder network is typically 750 ohms. Additional parasitic resistances are added by the package leads, wire bonds, conductor traces, etc. These parasitic resistances can introduce voltage drops causing gain and offset errors as large as 6 LSB's at the 12 -bit level. These IR drops can be compensated for by sensing the reference voltages at the $\mathrm{V}_{\text {TS }}$ and $\mathrm{V}_{\mathrm{BS}}$ reference sense pins and forcing the reference voltage an exact value as shown in Figure 4.

Since there is essentially zero current flowing through the sense line there is negligible voltage drop to the inverting input of the op-amp. The voltage at the inverting input of the op-amp, therefore, accurately represents the voltage at the top or bottom of the reference ladder network. The opamp drives the force input and forces the voltages at the ends of the reference ladder network to equal the voltage at the op-amps non-inverting input, plus or minus the opamps input offset voltage. When using this reference
configuration with a low offset voltage op-amp, gain and offset errors below 0.5 LSB are readily obtainable.

The 0.1 and $10 \mu \mathrm{~F}$ capacitors on the force inputs provide high frequency decoupling of the reference ladder network. The $500 \Omega$ force resistors isolate the op-amp from the large capacitive load. The $0.01 \mu \mathrm{~F}$ and $1 \mathrm{k} \Omega$ network ensures stability at high frequencies. The VR/16 output should be bypassed to analog ground with a $0.1 \mu \mathrm{~F}$ ceramic capacitor. All bypass capacitors should be located as close to the pins as possible to minimize noise on the reference ladder.
If the ADS-230/-231 is used in a frequency domain application then the circuit shown in Figure 3 maybe used. This circuit will introduce several LSB's of gain and offset error, but the dynamic performance will be unaffected.

The reference inputs are fully differential and define the fullscale range of the input signal. The maximum range can be up to 5 volts, or when required any span within the 0 to 5 V limit may be used. When using lower voltage spans the noise performance will degrade. See the Typical Performance Curves.

## Timing

The ADS-230/-231 has two modes of operation as shown in Figure 5, 6, 7 and 8.

In the Interrupt Interface mode, as shown in Figure 5, the falling edge of $\mathrm{S} / \mathrm{H}$ holds the input voltage and initiates a conversion when CS is held low. At the end of conversion, the EOC output goes high and the INT output goes low,


Figure 5. Interrupt Interface Timing ( $M D=0, O E=1$ )


Figure 7. $\overline{\mathrm{CS}}$ Setup \& Hold Timing for $\mathrm{S} / \overline{\mathrm{H}}, \overline{\mathrm{RD}}$ and OE
indicating that the conversion results are latched and may be read by pulling $\overline{R D}$ low. The falling edge of $\overline{R D}$ resets the INT line.

The High Speed Interface mode is shown in Figure 6. In this mode the output data is always present, and the $\overline{\mathrm{INT}}$ to RD delay is eliminated.
The control logic decoding section is shown in Figure 8.


Figure 6. High-speed Interface Timing ( $M D=0, O E=1, \overline{C S}=0, \overline{R D}=0$ )


Figure 8. ADS Control Logic

## Power Supply

The ADS-230 and ADS-231 are designed to operate off a single +5 V supply. To guarantee proper operation of the converters, only one power supply should be used. If separate analog and digital supplies are used, then the converter must be powered up with the analog supply. The absolute maximum ratings states that all inputs must be between GND -300 mV and VS +300 mV . When the converter power supply is turned off the maximum input becomes $\pm 300 \mathrm{mV}$, which in turn requires that the devices connected to the converter have power removed before power to the converter is removed.

There are two analog pins AVs and one digital supply pin DVs. This allows for separate bypassing of the analog and digital sections of the circuit. Both AV s pins should be bypassed to ground with $0.1 \mu \mathrm{~F}$ ceramic capacitors. At least one of the AVs pins should be bypassed with a $10 \mu \mathrm{~F}$ tantalum capacitor. The DVs input should be bypassed with a $0.1 \mu \mathrm{~F}$ ceramic capacitor in parallel with a $10 \mu \mathrm{~F}$ tantalum capacitor. All bypass capacitor should be located as close to the converter as possible.
There are two analog ground pins (AGND), three digital ground pins for the control inputs (DGNDC), and one digital ground pin for the data output lines (DGNDD). Separating the analog section from the digital sections reduces digital
interference in the analog circuitry thereby improving the dynamic performance of the converter. When driving a high capacitance digital data bus buffering the output data lines maybe necessary to minimize the DVs and DGND current spikes generated each conversion to charge the data bus capacitance.
These large current spikes will couple back to the analog circuitry increasing the converter noise level. Separating the digital outputs from the digital inputs reduces the possibility of ground bounce from the data lines causing jitter on the S/H input. The digital ground planes should be tied together at the digital ground pins. The analog ground plane should be tied to the DGNDD ground plane at the ground return strap for the power supply.

## S/H Input

The clock source driving the S/H input must be free of jitter. For best performance, a crystal oscillator is recommended. For the ADS-230 and ADS-231, a 1.0 and 1.5 Mhz square wave will provide a good signal for the respective S/H inputs. In both cases, as long as the duty cycle is near $50 \%$, the S/F pulse widths fall under the maximum allowed. When operating the ADS-230 below 910 kHz or the ADS231 below 1.25 MHz , the $\mathrm{S} / \overline{\mathrm{H}}$ pulse widths must be less than half the respective sample periods.


SNR and THD


Conversion Time
vs. Temperature







Note: Unless otherwise stated, the following conditions apply:
$D V s=A V s=5.0 \mathrm{~V}$
$\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$
$\mathrm{fs}=1.0 \mathrm{MHz}$
fin $=0 d B$ from full scale



Typical Performance Curves for ADS-230



SNR and THD








Typical Performance Curves for ADS-231


Note: Unless otherwise stated, the following conditions apply:

$$
\begin{gathered}
\mathrm{DV}=\mathrm{AV} \mathrm{~s}=5.0 \mathrm{~V} \\
\mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}
\end{gathered}
$$



Typical Performance Curves, ADS-230/-231

MECHANICAL DIMENSIONS INCHES (mm)


## ORDERING INFORMATION

| Model | Throughput Rate | Operating Temperature Range |
| :--- | :---: | :---: |
| ADS-230 | 1.0 MHz | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ |
| ADS-231 | 1.5 MHz | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ |

ISO 9001
R E G I S T E R E D

DATEL, Inc. 11 Cabot Boulevard, Mansfield, MA 02048-1151 Tel: (508) 339-3000 (800) 233-2765 Fax: (508) 339-6356 Internet:www.datel.com Email: sales@datel.com Data sheet fax back: (508) 261-2857

DATEL (UK) LTD. Tadley, England Tel: (01256)-880444
DATEL S.A.R.L. Montigny Le Bretonneux, France Tel: 01-34-60-01-01 DATEL GmbH Munchen, Germany Tel: 89-544334-0
DATEL KK Tokyo, Japan Tel: 3-3779-1031, Osaka Tel: 6-354-2025

